

Chip NTC Thermistors (Protection Device)

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NTCG104EF104FTDSX



Applications Automotive Grade

125°C 125°C

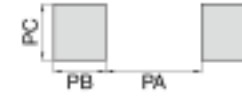
Features UL Certificate

AEC-Q200 AEC-Q200

Series NTCG

Status Production

Brand TDK



Images are for reference only and show example products.

[3D Model](#)

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Documents

- Catalog
- RoHS Certificate
- SVHC/REACH Certificate
- Selection Guide
- [Application Note] How to Use Temperature Protection Devices : Chip NTC Thermistors **Hot**
- RT Sheet

Technical Support Tools

- [Simulation Tool] Chip NTC Thermistor Simulation

Size	
Length(L)	1.00mm ±0.05mm
Width(W)	0.50mm ±0.05mm
Thickness(T)	0.50mm ±0.05mm
Terminal Width(B)	0.10mm Min.
Recommended Land Pattern (PA)	0.50mm ±0.10mm
Recommended Land Pattern (PB)	0.50mm ±0.10mm
Recommended Land Pattern (PC)	0.50mm ±0.10mm

Electrical Characteristics	
Resistance [at 25°C]	100kΩ
Resistance Tolerance	±1%
B value (Typ.) [25/50°C]	4250K
B value (Typ.) [25/85°C]	4308K
B value (Typ.) [25/100°C]	4327K
B value Tolerance	±1%
Max. Electric Power [at 25°C]	100mW
Permissible Operating Current [at 25°C]	100μA
Thermal Dissipation Constant [at 25°C]	1mW/°C 1mW/K

Other	
Max. Operating Temperature	125°C
Soldering Method	Reflow
UL File No.	E250289
AEC-Q200	Yes
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	10000pcs
Weight	0.0013g



- Selection Guides
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